

Connector for miniSD™ Card

SCJB Series



Low-profile type with a thickness of 2.15mm features high reliability contact structure.

For SD Memory Card

For miniSD™ Card

For microSD™ Card

For W-SIM

For Memory Stick Micro™

For Memory Stick™

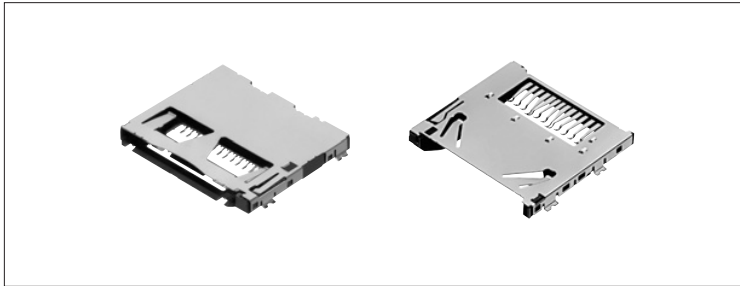
Combine Type

For Compact Flash™

For PC cards supporting CardBus

For Express Card™

For CMOS Camera Module



Features

- Media half-lock structure stops media from flying out during ejection, preventing the dropping and loss of media.
- Media detection switch adopts a highly reliable structure where the contact slides at ON/OFF to ensure detection of media insertion timing.
- Strong card-lock with high shock resilience.
- Compact size and low-profile.

Applications

- For digital still cameras, digital camcorders, mobile phones, PCs and personal digital assistants
- For portable memory players

Typical Specifications

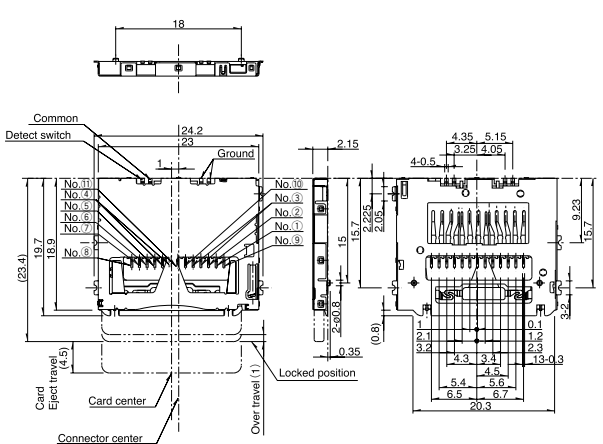
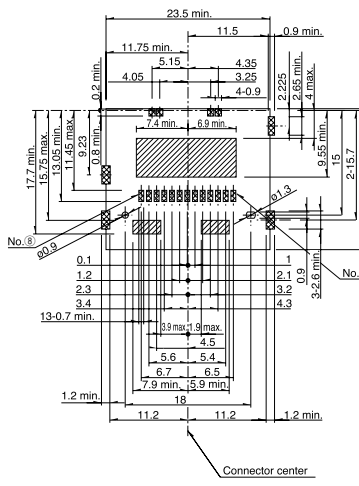



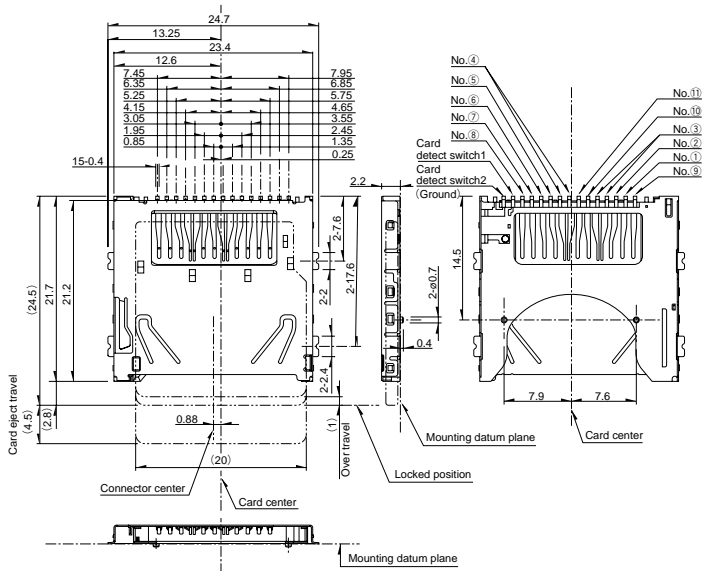
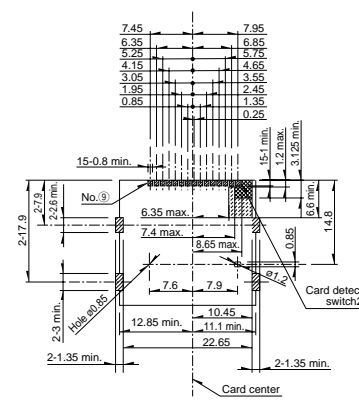




Items		Specifications	
Structure	Applicable media	miniSD™ Card	
	Mounting type	Surface mounting type	
	Mounting style	Standard mount/Reverse mount	
	Media ejection structure	Push-push type	
Performance	Operating temperature range	-25°C to +70°C	
	Voltage proof	500V AC 1minute	
	Insulation resistance (Initial)	1,000MΩ min.	
	Contact resistance (Initial)	Connector contacts	100mΩ max.
		Detection switch	500mΩ max.
Insertion and removal cycle	10,000cycles		

Product Line

Media ejection structure	Mounting style	Stand-off (mm)	Packing system	Product No.	Drawing No.
Push-push type	Standard mount	0	Taping	SCJB1B0301	1
	Reverse mount			SCJB2B0201	2

Dimensions

Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
1	<p>Standard mount</p> 	 <p>  Land area  No pattern area  No part mounting area </p>
2	<p>Reverse mount</p> 	 <p>  Land area  Ground area  No pattern area  No part mounting area </p>

For SD Memory Card

For miniSD™ Card

For microSD™ Card

For W-SIM

For Memory Stick™ Micro™

For Memory Stick™

Combine Type

For Compact Flash™

For PC cards supporting CardBus

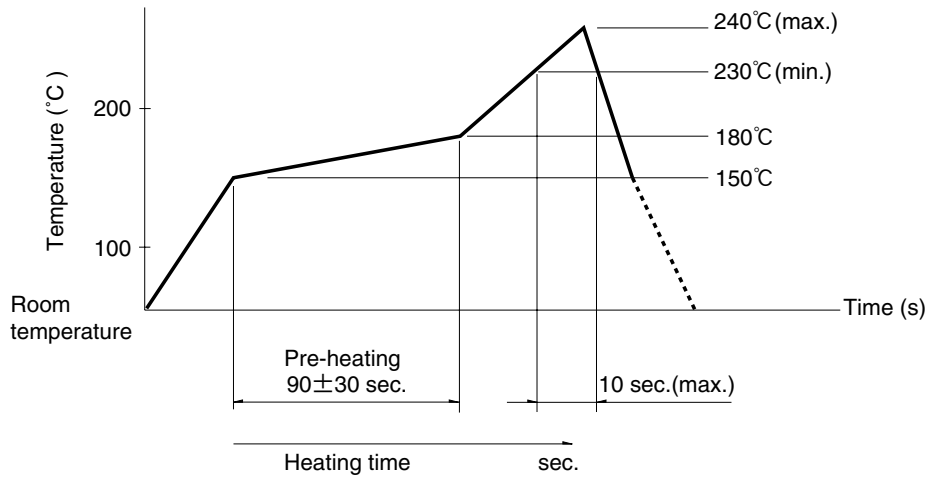
For Express Card™

For CMOS Camera Module

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile (Surface of products).



For SD Memory Card

For miniSD™ Card

For microSD™ Card

For W-SIM

For Memory Stick Micro™

For Memory Stick™

Combine Type

For Compact Flash™

For PC cards supporting CardBus

For Express Card™

For CMOS Camera Module

Cautions

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. Avoid use of water-soluble soldering flux, since it may corrode the product.
3. Check and conform to reflow soldering requirements under actual mass production conditions.
4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
5. This product has been designed and manufactured for use in ordinary electronic equipment, such as AV equipment, electric home appliances, office machines and communication equipment. In case of using the products for highly sensitive applications such as medical, aviation, aerospace and security, the set makers shall require to include measures necessary to meet product safety requirements of such specific applications. Such measure may include additional protection circuits and redundant circuits, for example.
6. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.